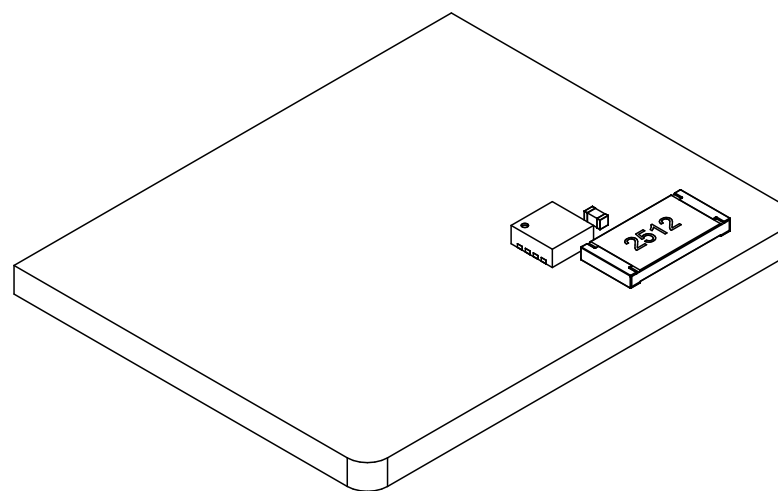
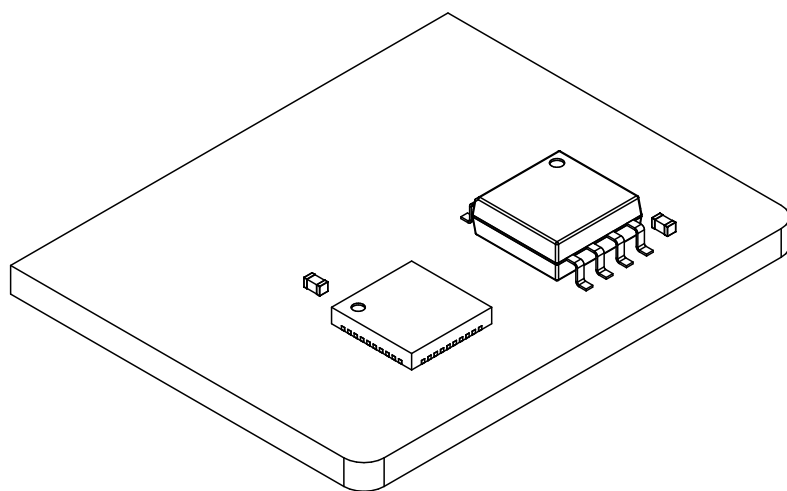


ESP32C6_CPA_Cartridge (2.0)

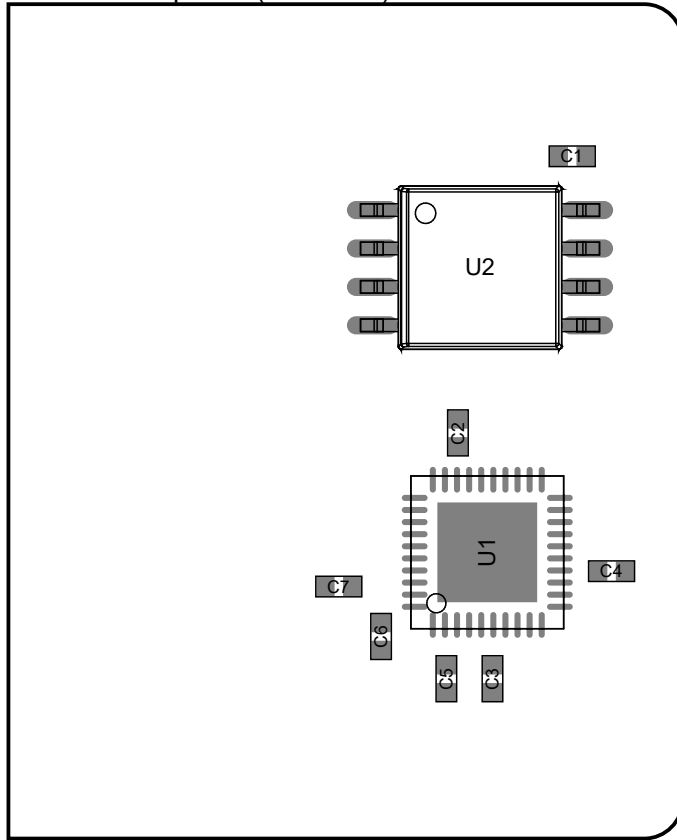


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|------------------|---------------------------|
| Project | ESP32C6_CP A_Cartridge |
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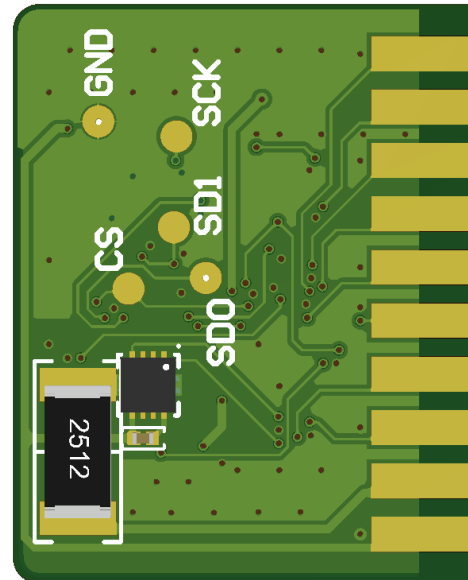
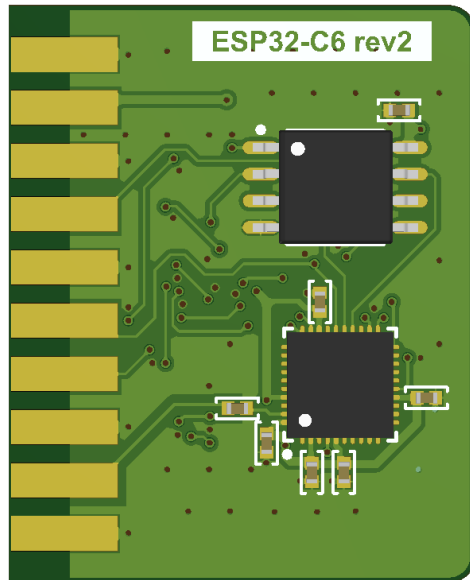
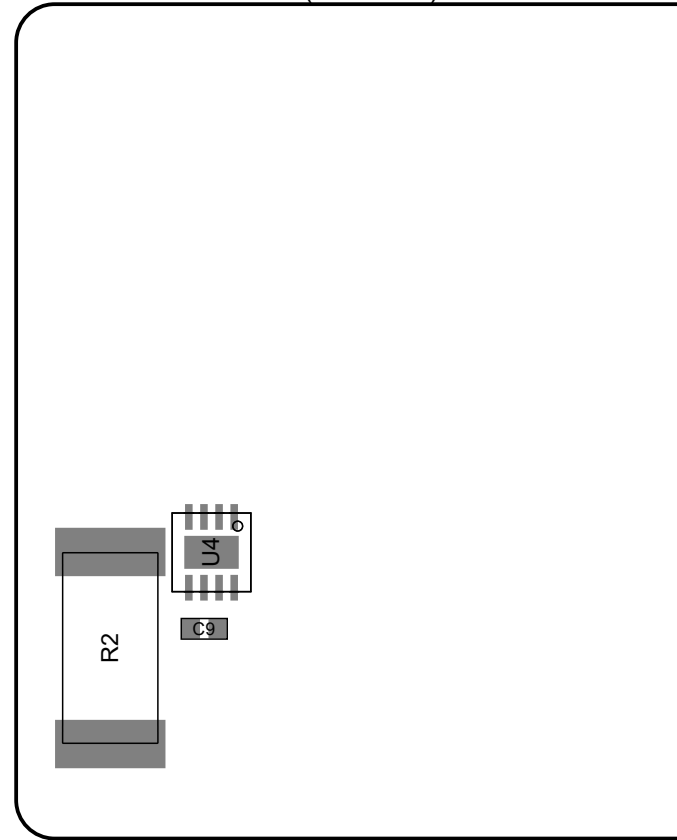


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View from Top side (Scale 4:1)



View from Bottom side (Scale 4:1)



| | |
|-----------------|---------------------------|
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Bill Of Materials

| Line # | Designator | Quantity | Footprint | Tolerance | Value | Manufacturer | Material | Part Name |
|--------|------------|----------|-------------------------|-----------|-------|---------------------------|----------|----------------|
| 1 | C1, C9 | 2 | C0402 | ±10% | 100nF | Samsung Electro-Mechanics | X7R | C1525 |
| 2 | C7 | 1 | C0402 | ±10% | 10nF | Samsung Electro-Mechanics | X7R | C15195 |
| 3 | R2 | 1 | R2512 | 5% | 30 | FOJAN | | FRC2512J300 TS |
| 4 | U1 | 1 | QFN40P500X500X90_HS-41N | | | Espressif | | ESP32-C6 |
| 5 | U2 | 1 | SOIC127P790X216-8N | | | Winbond | | W25Q32JVSSIQS |
| 6 | U4 | 1 | SON50P250X100_HS-9N | | | Sensirion | | STS35-DIS |

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
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Layer Stack Legend

| Material | Layer | Thickness | Dielectric Material | Type | Gerber |
|------------------|---------------------|----------------|---------------------|----------------|------------|
| | Top Overlay | | | Legend | GTO |
| Surface Material | Top Solder | 0.020mm | Solder Resist | Solder Mask | GTS |
| Copper | Top Layer | 0.035mm | | Signal | GTL |
| Prepreg | | 0.099mm | PP-006 | Dielectric | |
| CF-004 | Layer 1 | 0.015mm | | Internal Plane | GP1 |
| | | 1.265mm | FR-4 | Dielectric | |
| CF-004 | Layer 2 | 0.015mm | | Internal Plane | GP2 |
| Prepreg | | 0.099mm | PP-006 | Dielectric | |
| Copper | Bottom Layer | 0.035mm | | Signal | GBL |
| Surface Material | Bottom Solder | 0.020mm | Solder Resist | Solder Mask | GBS |
| | Bottom Overlay | | | Legend | GBO |

Total thickness: 1.604mm

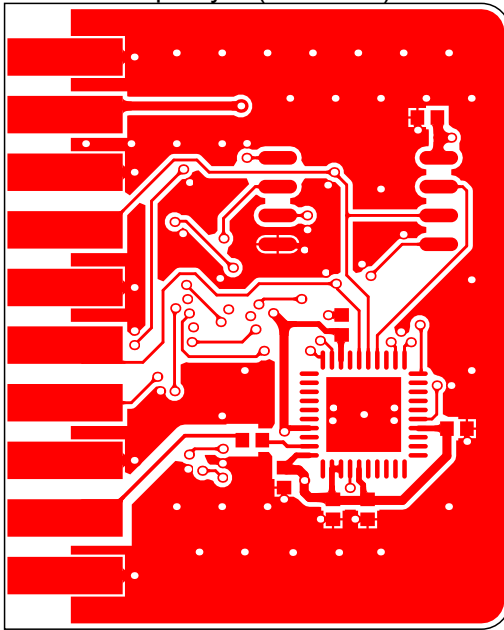
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|------------------|---------------------------|
| Project | ESP32C6_CP A_Cartridge |
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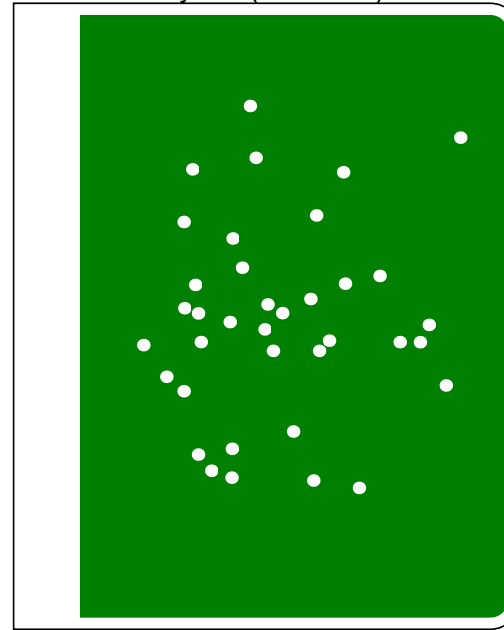
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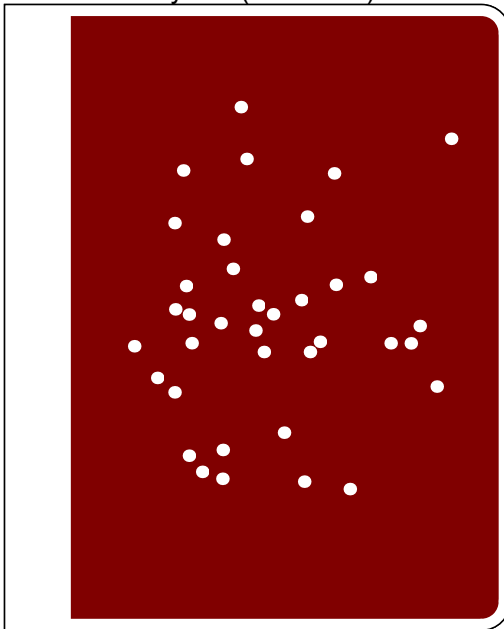
Top Layer (Scale 3:1)



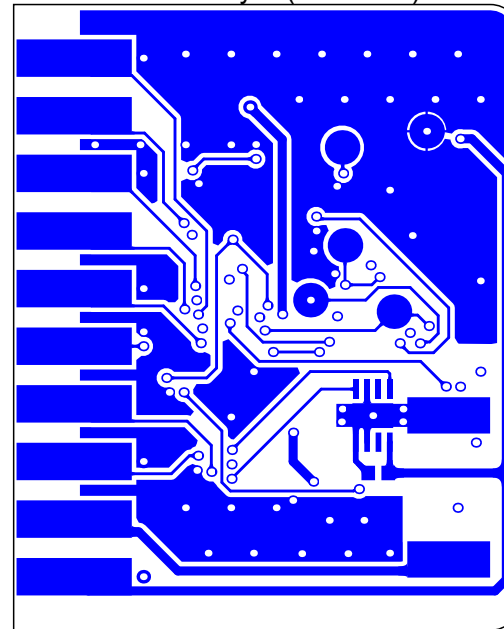
Layer 1 (Scale 3:1)



Layer 2 (Scale 3:1)



Bottom Layer (Scale 3:1)



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